

A modular semiconductor die package is provided. The semiconductor die package includes a polymer base for mounting at least one semiconductor die. A polymer cap is operatively secured over the base forming a cavity. The cap includes a light transmissive member operatively positioned to allow light of predetermined wavelengths to pass between at least a portion of the surface of the die and the light transmissive member. A plurality of conductive leads extend through the base to form connections with the semiconductor die(s) positioned in the cavity.

[illegible]